IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information					
Supplie	r Information														
Company name* Company				pany unique ID			Unique ID Authority					Response Date*			
onsemi												2023-06-08			
Contact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ve Date		ring Site	Weight*		UOM	Unit Type	
		FNB815	60T3	IPM SPM8 600V 15A LL			2023-06-08			СРА		3	320.116	mg	Each
Manufa	cturing Proccess Informat	tion						,				,		,	'
	Terminal Plating / Grid Array Material		erminal Base Alloy J-STD-02		-STD-020 MSI	Rating	Peak Process Body Temper		dy Temperatu	ture Max Time at Peak Te		Temperatu	re Numb	er of Reflow Cyc	eles
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C		30 seco		second	s 3				
Comments	3														
or more	information regarding material	composition	please refer to	page 3					·						

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier pro											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	21.6159	mg	Supplier	Silicon (Si)	7440-21-3		21.6159	mg
Die Attach Solder	40.0	mg	Supplier	Silver (Ag)	7440-22-4		1	mg
			A	Lead (Pb)	7439-92-1	7a	37	mg
			Supplier	Tin (Sn)	7440-31-5		2	mg
Epoxy	2.0	mg	Supplier	Silver (Ag)	7440-22-4		1.6	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.4	mg
Lead Frame	1450.0	mg	Supplier	Silver (Ag)	7440-22-4		365.4	mg
			Supplier	Copper (Cu)	7440-50-8		1084.6	mg
Mold Compound-Black	2264.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		135.84	mg
			Supplier	Carbon Black (C)	1333-86-4		22.64	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		135.84	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		158.48	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1811.2001	mg
Plating	22.5	mg	Supplier	Tin (Sn)	7440-31-5		22.5	mg
Wire Bond - Cu	20.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.4	mg
			Supplier	Copper (Cu)	7440-50-8		19.6	mg